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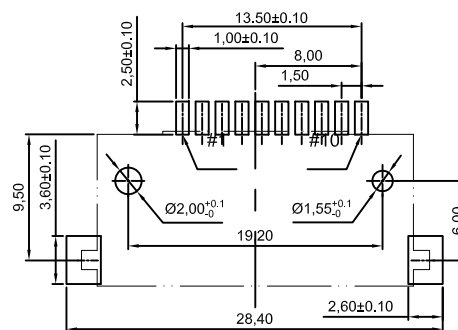
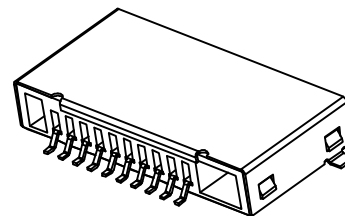
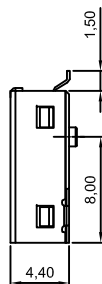
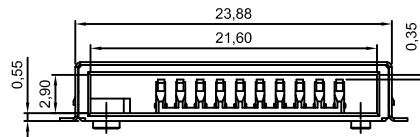
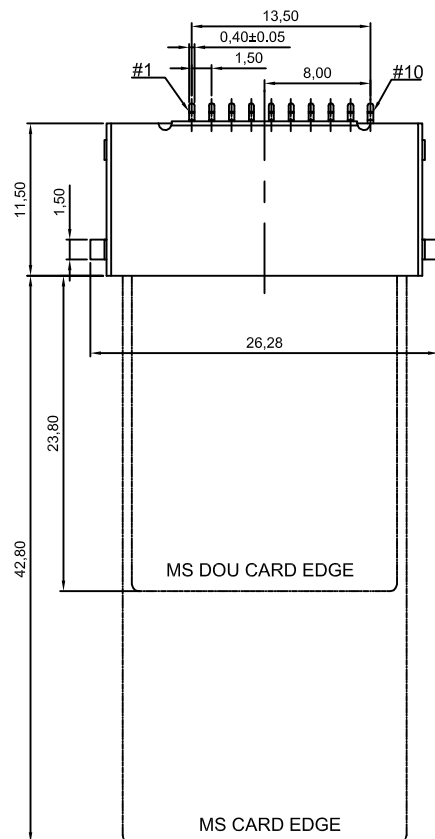
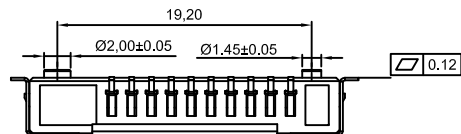
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REV.	ECN. NO.	NAME	DATE
A0	NEW	sina Li	2009.05.16
A1	FPE1007006	sina Li	2010.07.06



P.C.B Layout

MS CARD PIN DESIGN

Pin No.	MS CARD Name	MS PRO Name	Pin No.	MS CARD Name	MS PRO Name
#1	VSS	VSS	#6	VSS	VSS
#2	BS	BS	#7	RESERVE	DATE3
#3	VCC		#8	SCLK	SCLK
#4	DIO	DATE1	#9	VCC	VCC
#5		DATE0	#10	VSS	VSS

NOTES:

- 1.MATERIAL
HOUSING: HIGH TEMPERATURE THERMOPLASTIC.
CONTACT: COPPER ALLOY.
SHELL: COPPER ALLOY.
- 2.PLATING
CONTACT AREA: GOLD PLATED OVER NI.
SOLDER TAIL: 100u" MIN Sn PLATED OVER NI.
SPEC SEE ORDERING INFORMATION.
SHELL SOLDER AREA: GOLD PLATED OVER NI.
- 3.RATING
CURRENT RATING: 0.5A
VOLTAGE RATING: 250VRM
OPERATING TEMPERATURE: -55°C-85%5DC
- 4.SPECIFICATION
CONTACT RESISTANCE: 40mΩ max
DIELECTRIC WITHSTANDING VOLTAGE: 500VAC
INSULATION RESISTANCE: 100MΩ Min
INSERTION FORCE: 12N Max.
SEPARATION FORCE: 2N Min.

Ordering Information:

MDC 0 - 10 M X - W G 0 0 - 1 0 - X

0=Normal Type
1=Reverse Type

Contact Area Plating

- 1=Gold Flash
- 2=Gold Plating 3u" Min
- 3=Gold Plating 5u" Min
- 4=Gold Plating 10u" Min
- 5=Gold Plating 15u" Min

Omit--Commonly
5--Unleaded Manufacturing
Process(ROHS)
Q--Unleaded Manufacturing
Process(SS-00256 Standard)

0=NORMAL TYPE

W=White Color

GENERAL TOLERANCE:

.0 ±0.38
.00 ±0.25
.000 ±0.10
ANGLE ±3.00°
CUSTOMER COPY

DRAWN:

APPROVAL:

DATE: 2010.07.06

东莞市涪程电子科技有限公司
DONG GUAN FU CHENG ELECTRONIC CO., LTD

TITLE:

Memory Stick+Memory stick Duo Card
2 IN 1 FOR 1 CAV Normal type With Cover

PART NO:

MDCO-10MX-WG00-10-X

SIZE

A1

UNIT: mm

REV: A0

SCALE:

SHEET:

PROJECTION:

